

MM74HC32 Quad 2-Input OR Gate

General Description

The MM74HC32 OR gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs providing high noise immunity and the ability to drive 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

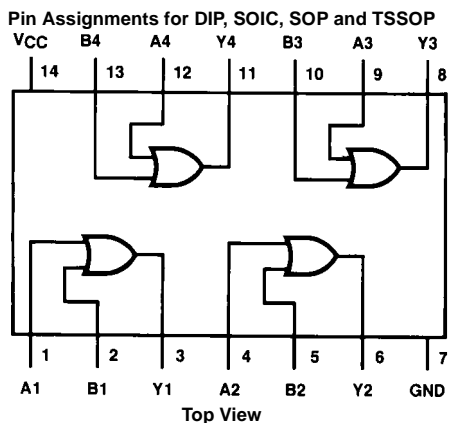
- Typical propagation delay: 10 ns
- Wide power supply range: 2–6V
- Low quiescent current: 20 μ A maximum (74HC Series)
- Low input current: 1 μ A maximum
- Fanout of 10 LS-TTL loads

Ordering Code:

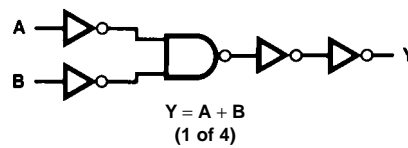
Order Number	Package Number	Package Description
MM74HC32M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC32MX_NL	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC32SJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC32MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC32MTCX_NL	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC32N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
MM74HC32N_NL	N14A	Pb-Free 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

Connection Diagram



Logic Diagram



Absolute Maximum Ratings (Note 1)		Recommended Operating Conditions		
Supply Voltage (V_{CC})	-0.5 to + 7.0V	Min	Max	Units
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$	2	6	V
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$	0	V_{CC}	V
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA	(V_{IN}, V_{OUT})		
DC Output Current, per pin (I_{OUT})	± 25 mA	Operating Temperature Range (T_A)		
DC V_{CC} or GND Current, per pin (I_{CC})	± 50 mA	-40	+85	$^{\circ}C$
Storage Temperature Range (T_{STG})	-65 $^{\circ}C$ to +150 $^{\circ}C$	Input Rise or Fall Times		
Power Dissipation (P_D)		(t_r, t_f) $V_{CC} = 2.0V$	1000	ns
(Note 3)	600 mW	$V_{CC} = 4.5V$	500	ns
S.O. Package only	500 mW	$V_{CC} = 6.0V$	400	ns
Lead Temperature (T_L)	260 $^{\circ}C$	Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur. Note 2: Unless otherwise specified all voltages are referenced to ground. Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/ $^{\circ}C$ from 65 $^{\circ}C$ to 85 $^{\circ}C$.		

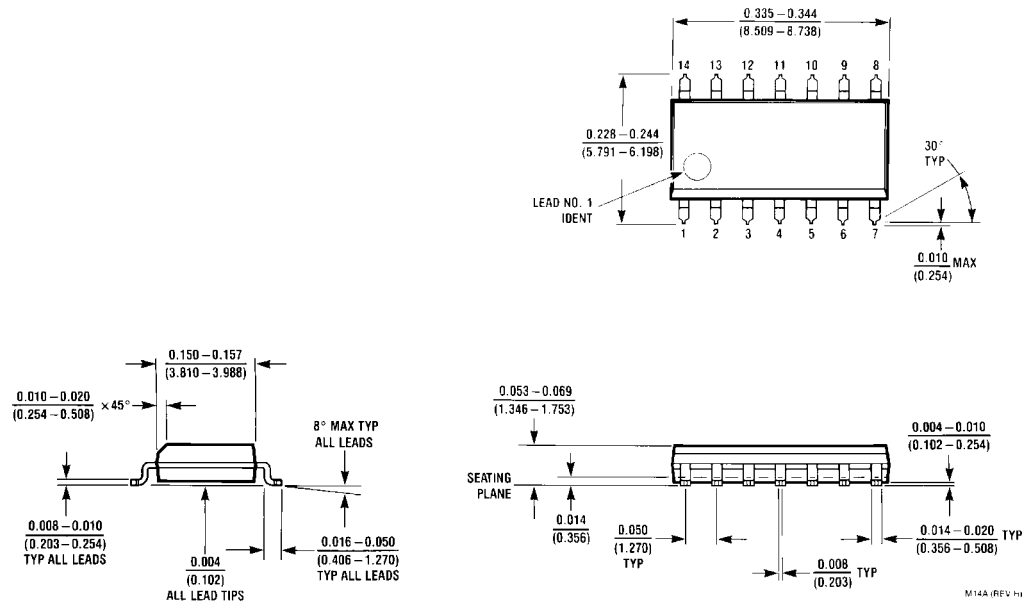
DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^{\circ}C$		$T_A = -40$ to $85^{\circ}C$		Units
				Typ	Guaranteed Limits			
V_{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	V	
			4.5V		3.15	3.15	V	
			6.0V		4.2	4.2	V	
V_{IL}	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	V	
			4.5V		1.35	1.35	V	
			6.0V		1.8	1.8	V	
V_{OH}	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu A$	2.0V	2.0	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	V	
		6.0V	6.0	5.9	5.9	V		
		$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0$ mA $ I_{OUT} \leq 5.2$ mA	4.5V	4.7	3.98	3.84	V	
6.0V	5.2		5.48	5.34	V			
V_{OL}	Maximum LOW Level Output Voltage	$V_{IN} = V_{IL}$ $ I_{OUT} \leq 20 \mu A$	2.0V	0	0.1	0.1	V	
			4.5V	0	0.1	0.1	V	
		6.0V	0	0.1	0.1	V		
		$V_{IN} = V_{IL}$ $ I_{OUT} \leq 4.0$ mA $ I_{OUT} \leq 5.2$ mA	4.5V	0.2	0.26	0.33	V	
6.0V	0.2		0.26	0.33	V			
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		± 0.1	± 1.0	μA	
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	μA	

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

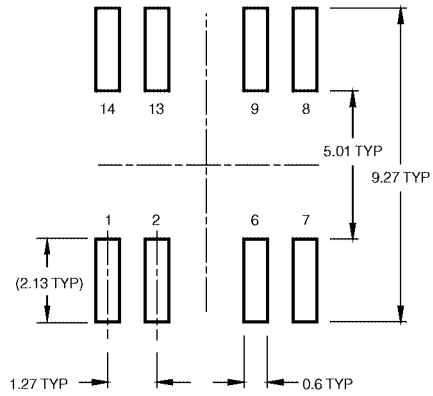
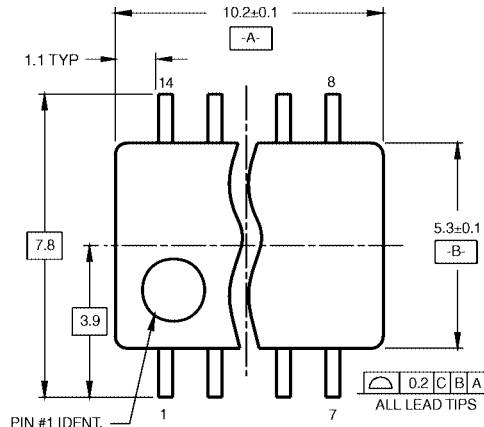
AC Electrical Characteristics							
$V_{CC} = 5V, T_A = 25^{\circ}C, C_L = 15 \text{ pF}, t_r = t_f = 6 \text{ ns}$							
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units		
t_{PHL}, t_{PLH}	Maximum Propagation Delay		10	18	ns		
AC Electrical Characteristics							
$V_{CC} = 2.0V \text{ to } 6.0V, C_L = 50 \text{ pF}, t_r = t_f = 6 \text{ ns (unless otherwise specified)}$							
Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^{\circ}C$		$T_A = -40 \text{ to } 85^{\circ}C$	Units
				Typ	Guaranteed Limits		
t_{PHL}, t_{PLH}	Maximum Propagation Delay		2.0V	30	100	125	ns
			4.5V	12	20	25	ns
			6.0V	9	17	21	ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	95	ns
			4.5V	8	15	19	ns
			6.0V	7	13	16	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		50			pF
C_{IN}	Maximum Input Capacitance			5	10	10	pF
<p>Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.</p>							

Physical Dimensions inches (millimeters) unless otherwise noted

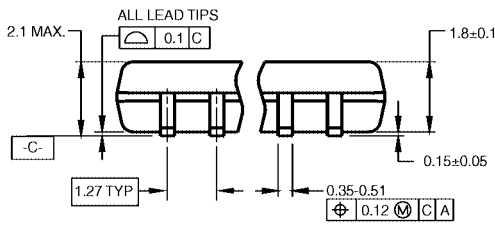


14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

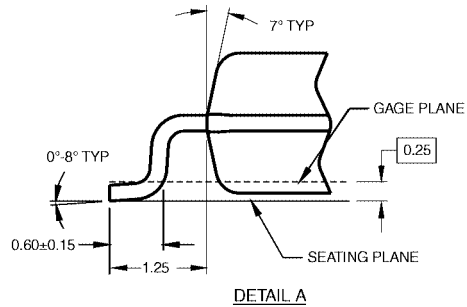
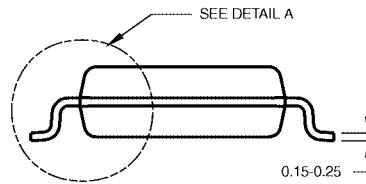
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

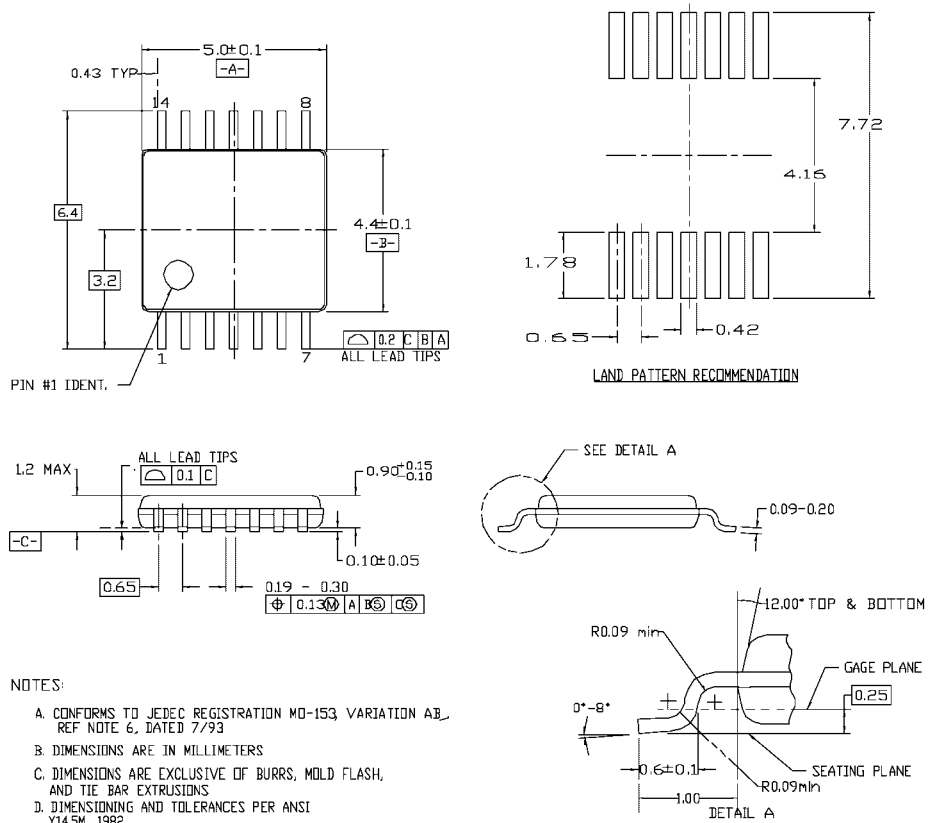
NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

**Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

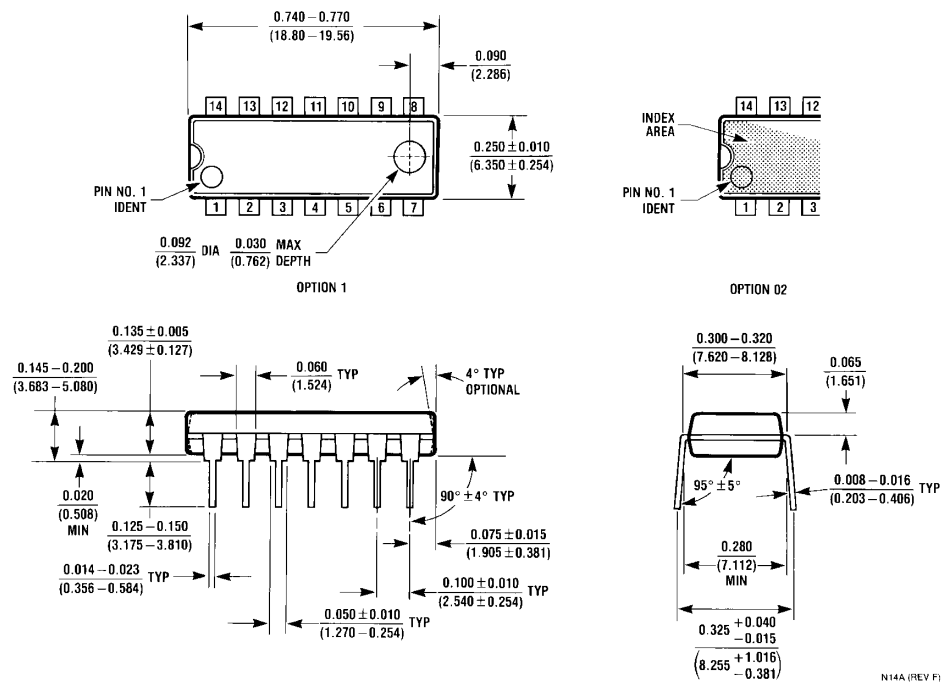


- NOTES:
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93
 - DIMENSIONS ARE IN MILLIMETERS
 - DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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